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Data Sheet

FEATURES

8 ADCs integrated into 1 package 114 mW ADC power per channel at 65 MSPS SNR = 70 dB (to Nyquist) ENOB = 11.3 bits SEDR = 80 dBcExcellent linearity: $DNL = \pm 0.3 LSB$ (typical), $INL = \pm 0.4 LSB (typical)$ Serial LVDS (ANSI-644, default) Low power, reduced signal option (similar IEEE 1596.3) Data and frame clock outputs 325 MHz full-power analog bandwidth 2 V p-p input voltage range 1.8 V supply operation Serial port control Full-chip and individual-channel power-down modes **Flexible bit orientation** Built-in and custom digital test pattern generation Programmable clock and data alignment **Programmable output resolution** Standby mode

APPLICATIONS

Medical imaging and nondestructive ultrasound Portable ultrasound and digital beam-forming systems Quadrature radio receivers Diversity radio receivers Tape drives Optical networking Test equipment

GENERAL DESCRIPTION

The AD9222 is an octal, 12-bit, 40/50/65 MSPS analog-todigital converter (ADC) with an on-chip sample-and-hold circuit designed for low cost, low power, small size, and ease of use. The product operates at a conversion rate of up to 65 MSPS and is optimized for outstanding dynamic performance and low power in applications where a small package size is critical.

The ADC requires a single 1.8 V power supply and LVPECL-/ CMOS-/LVDS-compatible sample rate clock for full performance operation. No external reference or driver components are required for many applications.

The ADC automatically multiplies the sample rate clock for the appropriate LVDS serial data rate. A data clock output (DCO) for capturing data on the output and a frame clock output (FCO) for signaling a new output byte are provided. Individual-channel power-down is supported and typically consumes less than 2 mW when all channels are disabled.

Octal, 12-Bit, 40/50/65 MSPS Serial LVDS 1.8 V A/D Converter

AD9222

FUNCTIONAL BLOCK DIAGRAM



The ADC contains several features designed to maximize flexibility and minimize system cost, such as programmable clock and data alignment and programmable digital test pattern generation. The available digital test patterns include built-in deterministic and pseudorandom patterns, along with custom userdefined test patterns entered via the serial port interface (SPI).

The AD9222 is available in an RoHS compliant, 64-lead LFCSP. It is specified over the industrial temperature range of -40° C to $+85^{\circ}$ C.

PRODUCT HIGHLIGHTS

- 1. Small Footprint. Eight ADCs are contained in a small, space-saving package.
- 2. Low power of 114 mW/channel at 65 MSPS.
- 3. Ease of Use. A data clock output (DCO) is provided that operates at frequencies of up to 390 MHz and supports double data rate (DDR) operation.
- 4. User Flexibility. The SPI control offers a wide range of flexible features to meet specific system requirements.
- 5. Pin-Compatible Family. This includes the AD9212 (10-bit) and AD9252 (14-bit).

Rev. F

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AD9222* PRODUCT PAGE QUICK LINKS

Last Content Update: 02/23/2017

COMPARABLE PARTS

View a parametric search of comparable parts.

EVALUATION KITS

AD9222 Evaluation Board

DOCUMENTATION

Application Notes

- AN-1142: Techniques for High Speed ADC PCB Layout
- AN-282: Fundamentals of Sampled Data Systems
- AN-345: Grounding for Low-and-High-Frequency Circuits
- AN-501: Aperture Uncertainty and ADC System Performance
- AN-715: A First Approach to IBIS Models: What They Are and How They Are Generated
- AN-737: How ADIsimADC Models an ADC
- AN-741: Little Known Characteristics of Phase Noise
- AN-742: Frequency Domain Response of Switched-Capacitor ADCs
- AN-756: Sampled Systems and the Effects of Clock Phase Noise and Jitter
- AN-812: MicroController-Based Serial Port Interface (SPI) Boot Circuit
- AN-827: A Resonant Approach to Interfacing Amplifiers to Switched-Capacitor ADCs
- AN-835: Understanding High Speed ADC Testing and Evaluation
- AN-905: Visual Analog Converter Evaluation Tool Version 1.0 User Manual
- AN-935: Designing an ADC Transformer-Coupled Front End

Data Sheet

 AD9222: Octal, 12-Bit, 40/50/65 MSPS Serial LVDS 1.8 V A/ D Converter Data Sheet

TOOLS AND SIMULATIONS \square

- Visual Analog
- AD9222 IBIS Models

REFERENCE MATERIALS

Technical Articles

• MS-2210: Designing Power Supplies for High Speed ADC

DESIGN RESOURCES

- AD9222 Material Declaration
- PCN-PDN Information
- Quality And Reliability
- Symbols and Footprints

DISCUSSIONS

View all AD9222 EngineerZone Discussions.

SAMPLE AND BUY

Visit the product page to see pricing options.

TECHNICAL SUPPORT 🖵

Submit a technical question or find your regional support number.

DOCUMENT FEEDBACK

Submit feedback for this data sheet.

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9/06—Revision 0: Initial Version

SPECIFICATIONS

AVDD = 1.8 V, DRVDD = 1.8 V, 2 V p-p differential input, 1.0 V internal reference, AIN = -0.5 dBFS, unless otherwise noted.

Table 1.	
----------	--

			AD9222-4	0		AD9222-	50		AD9222-6	5	
Parameter ¹	Temp	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
RESOLUTION		12			12			12			Bits
ACCURACY											
No Missing Codes	Full		Guarantee	d		Guarante	ed		Guarantee	d	
Offset Error	Full		±1	±8		±1	±8		±1	±8	mV
Offset Matching	Full		±3	±8		±3	±8		±3	±8	mV
Gain Error	Full		±0.4	±1.2		±1.5	±2.5		±3.5	±5	% FS
Gain Matching	Full		±0.3	±0.7		±0.3	±0.7		±0.4	±0.8	% FS
Differential Nonlinearity (DNL)	Full		±0.25	±0.5		±0.3	±0.65		±0.25	±0.6	LSB
Integral Nonlinearity (INL)	Full		±0.4	±1		±0.4	±1		±0.4	±1	LSB
TEMPERATURE DRIFT											
Offset Error	Full		±2			±2			±2		ppm/°C
Gain Error	Full		±17			±17			±17		ppm/°C
Reference Voltage (1 V Mode)	Full		±21			±21			±21		ppm/°C
REFERENCE											
Output Voltage Error (VREF = 1 V)	Full		±2	±30		±2	±30		±2	±30	mV
Load Regulation @ 1.0 mA (VREF = 1 V)	Full		3			3			3		mV
Input Resistance	Full		6			6			6		kΩ
ANALOG INPUTS											
Differential Input Voltage Range (VREF = 1 V)	Full		2			2			2		V р-р
Common-Mode Voltage	Full		AVDD/2			AVDD/2			AVDD/2		V
Differential Input Capacitance	Full		7			7			7		pF
Analog Bandwidth, Full Power	Full		325			325			325		MHz
POWER SUPPLY											
AVDD	Full	1.7	1.8	1.9	1.7	1.8	1.9	1.7	1.8	1.9	V
DRVDD	Full	1.7	1.8	1.9	1.7	1.8	1.9	1.7	1.8	1.9	V
IAVDD	Full		338	348.5		357.5	367.5		450	470	mA
IDRVDD	Full		51	53.6		53.5	56.2		56.6	60.5	mA
Total Power Dissipation (Including Output Drivers)	Full		700	722		740	760		910	950.5	mW
Power-Down Dissipation	Full		2	11		2	11		2	11	mW
Standby Dissipation ²	Full		83			89			100		mW
CROSSTALK	Full		-90			-90			-90		dB
CROSSTALK (Overrange Condition) ³	Full		-90			-90			-90		dB

¹ See the AN-835 Application Note, Understanding High Speed ADC Testing and Evaluation, for a complete set of definitions and how these tests were completed.

² This can be controlled via SPI.

³ Overrange condition is specific with 6 dB of the full-scale input range.

AC SPECIFICATIONS

AVDD = 1.8 V, DRVDD = 1.8 V, 2 V p-p differential input, 1.0 V internal reference, AIN = -0.5 dBFS, unless otherwise noted.

Table 2.

		A	D9222-4	0	A	D9222-5	50	P	D9222-	65	
Parameter ¹	Temp	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
SIGNAL-TO-NOISE RATIO (SNR)											
$f_{IN} = 2.4 \text{ MHz}$	Full		70.3			70.4			70.3		dB
f _{IN} = 19.7 MHz	Full	69.5	70.3		69.5	70.3		68.5	70.0		dB
$f_{IN} = 35 \text{ MHz}$	Full		69.9			70.0			69.8		dB
$f_{IN} = 70 \text{ MHz}$	Full		68.8			69.0			69.5		dB
SIGNAL-TO-NOISE AND DISTORTION RATIO (SINAD)											
$f_{IN} = 2.4 \text{ MHz}$	Full		70.0			70.0			69.5		dB
f _{IN} = 19.7 MHz	Full	68.7	70.0		68.5	70.0		66.8	69.4		dB
$f_{IN} = 35 \text{ MHz}$	Full		69.5			69.8			69.3		dB
$f_{IN} = 70 \text{ MHz}$	Full		68.0			68.5			69		dB
EFFECTIVE NUMBER OF BITS (ENOB)											
$f_{IN} = 2.4 \text{ MHz}$	Full		11.38			11.4			11.4		Bits
$f_{IN} = 19.7 \text{ MHz}$	Full	11.25	11.38		11.25	11.38		11.1	11.34		Bits
$f_{IN} = 35 \text{ MHz}$	Full		11.32			11.33			11.30		Bits
$f_{IN} = 70 \text{ MHz}$	Full		11.14			11.17			11.25		Bits
SPURIOUS-FREE DYNAMIC RANGE (SFDR)											
$f_{IN} = 2.4 \text{ MHz}$	Full		85			85			83		dBc
f _{IN} = 19.7 MHz	Full	73	85		73	84		70.5	80		dBc
$f_{IN} = 35 \text{ MHz}$	Full		80			83			80		dBc
$f_{IN} = 70 \text{ MHz}$	Full		76			77			75		dBc
WORST HARMONIC (Second or Third)											
$f_{IN} = 2.4 \text{ MHz}$	Full		-85			-85			-83		dBc
f _{IN} = 19.7 MHz	Full		-85	-74		-84	-73		-80	-70.5	dBc
$f_{IN} = 35 \text{ MHz}$	Full		-80			-83			-80		dBc
$f_{IN} = 70 \text{ MHz}$	Full		-76			-77			-75		dBc
WORST OTHER (Excluding Second or Third)											
$f_{IN} = 2.4 \text{ MHz}$	Full		-92			-92			-90		dBc
$f_{IN} = 19.7 \text{ MHz}$	Full		-92	-80		-92	-80		-90	-80	dBc
$f_{IN} = 35 \text{ MHz}$	Full		-92			-92			-90		dBc
$f_{IN} = 70 \text{ MHz}$	Full		-90			-90			-85		dBc
TWO-TONE INTERMODULATION DISTORTION (IMD)-											
AIN1 AND AIN2 = -7.0 dBFS											
$f_{IN1} = 15 \text{ MHz}, f_{IN2} = 16 \text{ MHz}$	25°C		80.0			80.0			80.0		dBc
$f_{IN1} = 70 \text{ MHz}, f_{IN2} = 71 \text{ MHz}$	25°C		77.0			77.0			75.0		dBc

¹ See the AN-835 Application Note, Understanding High Speed ADC Testing and Evaluation, for a complete set of definitions and how these tests were completed.

DIGITAL SPECIFICATIONS

AVDD = 1.8 V, DRVDD = 1.8 V, 2 V p-p differential input, 1.0 V internal reference, AIN = -0.5 dBFS, unless otherwise noted.

Table 3.

Parameter 1TempMinTypMaxMinTypMaxMinTypMaxUnitCLOCK INPUTS (CLK+, CLK-) Logic ComplianceCCMOS/LVDS/LVPECLCMOS/LVDS/LVPECLCMOS/LVDS/LVPECLCMOS/LVDS/LVPECLCMOS/LVDS/LVPECLDifferential Input Voltage2Full250250250250mV p-pInput Common-Mode VoltageFull1.21.21.21.2VInput Resistance (Differential)25°C202020kΩInput Capacitance25°C1.51.51.5pFLOGIC INPUTS (PDWN, SCLK/DTP)Inc3.61.23.61.23.6Logic 0 VoltageFull00.30.30.30.3V				AD922	22-40		AD922	22-50		AD922	2-65	
CLOCK INPUTS (CLK+, CLK-) Logic ComplianceCMOS/LVDS/LVPECLCMOS/LVDS/LVPECLCMOS/LVDS/LVPECLDifferential Input Voltage²Full250250250mV p-pInput Common-Mode VoltageFull1.21.21.2VInput Resistance (Differential)25°C2020kQInput Capacitance25°C1.51.51.5pFLOGIC INPUTS (PDWN, SCLK/DTP)Logic 1 VoltageFull1.23.61.23.6VLogic 0 VoltageFull00.30.30.3V	Parameter ¹	Temp	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
Logic ComplianceCMOS/LVDS/LVPECLCMOS/LVDS/LVPECLCMOS/LVDS/LVPECL $CMOS/LVDS/LVPECL$ $mV p-p$ Differential Input Voltage²Full 250 250 250 $mV p-p$ Input Common-Mode VoltageFull 1.2 1.2 1.2 V Input Resistance (Differential) 25° C 20 20 20 $k\Omega$ Input Capacitance 25° C 1.5 1.5 1.5 pF LOGIC INPUTS (PDWN, SCLK/DTP)Logic 1 VoltageFull 1.2 3.6 1.2 3.6 V Logic 0 VoltageFull 0 0.3 0.3 0.3 V	CLOCK INPUTS (CLK+, CLK–)											
Differential Input Voltage ² Full 250 250 mV p-p Input Common-Mode Voltage Full 1.2 1.2 1.2 V Input Resistance (Differential) 25°C 20 20 20 kΩ Input Capacitance 25°C 1.5 1.5 1.5 pF LOGIC INPUTS (PDWN, SCLK/DTP) Logic 1 Voltage Full 1.2 3.6 1.2 3.6 V Logic 0 Voltage Full 0 0.3 0.3 0.3 V	Logic Compliance		CN	NOS/LVD	S/LVPECL	CN	NOS/LVE	S/LVPECL	CN	IOS/LVD	S/LVPECL	
Input Common-Mode Voltage Full 1.2 1.2 1.2 V Input Resistance (Differential) 25°C 20 20 20 kΩ Input Capacitance 25°C 1.5 1.5 1.5 pF LOGIC INPUTS (PDWN, SCLK/DTP) Imput Capacitance Full 1.2 3.6 1.2 3.6 V Logic 1 Voltage Full 0 0.3 0.3 0.3 V	Differential Input Voltage ²	Full	250			250			250			mV p-p
Input Resistance (Differential) 25°C 20 20 kΩ Input Capacitance 25°C 1.5 1.5 1.5 pF LOGIC INPUTS (PDWN, SCLK/DTP) Imput Capacitance Imput Capacitance <td>Input Common-Mode Voltage</td> <td>Full</td> <td></td> <td>1.2</td> <td></td> <td></td> <td>1.2</td> <td></td> <td></td> <td>1.2</td> <td></td> <td>V</td>	Input Common-Mode Voltage	Full		1.2			1.2			1.2		V
Input Capacitance 25°C 1.5 1.5 pF LOGIC INPUTS (PDWN, SCLK/DTP) Image: Comparison of the second	Input Resistance (Differential)	25°C		20			20			20		kΩ
LOGIC INPUTS (PDWN, SCLK/DTP) Full 1.2 3.6 1.2 3.6 1.2 3.6 V Logic 0 Voltage Full 0 0.3 0.3 0.3 V	Input Capacitance	25°C		1.5			1.5			1.5		pF
Logic 1 Voltage Full 1.2 3.6 1.2 3.6 1.2 3.6 V Logic 0 Voltage Full 0 0.3 0.3 0.3 V	LOGIC INPUTS (PDWN, SCLK/DTP)											
Logic O Voltage Full 0 0.3 0.3 0.3 V	Logic 1 Voltage	Full	1.2		3.6	1.2		3.6	1.2		3.6	V
	Logic 0 Voltage	Full	0		0.3			0.3			0.3	V
Input Resistance 25°C 30 30 30 kΩ	Input Resistance	25°C		30			30			30		kΩ
Input Capacitance 25°C 0.5 0.5 0.5 pF	Input Capacitance	25°C		0.5			0.5			0.5		pF
LOGIC INPUT (CSB)	LOGIC INPUT (CSB)											
Logic 1 Voltage Full 1.2 3.6 1.2 3.6 V	Logic 1 Voltage	Full	1.2		3.6	1.2		3.6	1.2		3.6	V
Logic 0 Voltage Full 0 0.3 0.3 0.3 V	Logic 0 Voltage	Full	0		0.3			0.3			0.3	V
Input Resistance 25°C 70 70 70 kΩ	Input Resistance	25°C		70			70			70		kΩ
Input Capacitance 25°C 0.5 0.5 0.5 pF	Input Capacitance	25°C		0.5			0.5			0.5		pF
LOGIC INPUT (SDIO/ODM)	LOGIC INPUT (SDIO/ODM)											
Logic 1 Voltage Full 1.2 DRVDD+0.3 1.2 DRVDD+0.3 1.2 DRVDD+0.3 V	Logic 1 Voltage	Full	1.2		DRVDD+0.3	1.2		DRVDD+0.3	1.2		DRVDD+0.3	V
Logic 0 Voltage Full 0 0.3 0 0.3 0 0.3 V	Logic 0 Voltage	Full	0		0.3	0		0.3	0		0.3	V
Input Resistance 25°C 30 30 30 kΩ	Input Resistance	25°C		30			30			30		kΩ
Input Capacitance 25°C 2 2 2 pF	Input Capacitance	25°C		2			2			2		pF
LOGIC OUTPUT (SDIO/ODM) ³	LOGIC OUTPUT (SDIO/ODM) ³											
Logic 1 Voltage (I _{OH} = 800 μA) Full 1.79 1.79 1.79 V	Logic 1 Voltage ($I_{OH} = 800 \mu A$)	Full		1.79			1.79			1.79		V
Logic 0 Voltage ($I_{0L} = 50 \ \mu A$) Full 0.05 0.05 V	Logic 0 Voltage ($I_{OL} = 50 \mu A$)	Full			0.05			0.05			0.05	V
DIGITAL OUTPUTS $(D + x, D - x)$, (ANSI-644) ¹	DIGITAL OUTPUTS (D + x, D - x), (ANSI-644) ¹											
Logic Compliance LVDS LVDS LVDS	Logic Compliance			I VDS						IVDS		
Differential Output Voltage (V_{00}) Full 247 454 247 454 247 454 mV	Differential Output Voltage (Vop)	Full	247	1.00	454	247	2.00	454	247	1.00	454	mV
Output Offset Voltage (Vos) Full 1.125 1.375 1.125 1.375 1.125 1.375	Output Offset Voltage (V_{os})	Full	1.125		1.375	1.125		1.375	1.125		1.375	V
Output Coding (Default) Offset binary Offset binary Offset binary	Output Coding (Default)			Offset I	binarv		Offset	binarv		Offset b	pinary	-
DIGITAL OUTPUTS $(D + x, D - x)$.	DIGITAL OUTPUTS $(D + x, D - x)$.				,						,	
(Low Power, Reduced Signal Option) ¹	(Low Power, Reduced Signal Option) ¹											
Logic Compliance LVDS LVDS LVDS	Logic Compliance			LVDS			LVDS			LVDS		
Differential Output Voltage (V_{00}) Full 150 250 150 250 150 250 mV	Differential Output Voltage (Von)	Full	150	2.25	250	150	2.25	250	150	2.25	250	mV
Output Offset Voltage (Vos) Full 1.10 1.30 1.10 1.30 V	Output Offset Voltage (Vos)	Full	1.10		1.30	1.10		1.30	1.10		1.30	V
Output Coding (Default) Offset binary Offset binary Offset binary	Output Coding (Default)			Offset I	binary		Offset	binary		Offset b	oinary	

¹ See the AN-835 Application Note, *Understanding High Speed ADC Testing and Evaluation*, for a complete set of definitions and how these tests were completed. ² This is specified for LVDS and LVPECL only. ³ This is specified for 13 SDIO pins sharing the same connection.

SWITCHING SPECIFICATIONS

AVDD = 1.8 V, DRVDD = 1.8 V, 2 V p-p differential input, 1.0 V internal reference, AIN = -0.5 dBFS, unless otherwise noted.

Table 4.

			AD9222-40			AD9222-50			AD9222-65		
Parameter ¹	Temp	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
CLOCK ²											
Maximum Clock Rate	Full	40			50			65			MSPS
Minimum Clock Rate	Full			10			10			10	MSPS
Clock Pulse Width High (t_{EH})	Full		12.5			10.0			7.5		ns
Clock Pulse Width Low (t_{EL})	Full		12.5			10.0			7.5		ns
OUTPUT PARAMETERS ^{2, 3}											
Propagation Delay (t _{PD})	Full	1.5	2.3	3.1	1.5	2.3	3.1	1.5	2.3	3.1	ns
Rise Time (t _R) (20% to 80%)	Full		300			300			300		ps
Fall Time (t _F) (20% to 80%)	Full		300			300			300		ps
FCO Propagation Delay (t_{FCO})	Full	1.5	2.3	3.1	1.5	2.3	3.1	1.5	2.3	3.1	ns
DCO Propagation Delay $(t_{CPD})^4$	Full		t _{FCO} + (t _{SAMPLE} /24)			t _{FCO} + (t _{SAMPLE} /24)			t _{fco} + (t _{sample} /24)		ns
DCO to Data Delay $(t_{DATA})^4$	Full	(t _{sample} /24) - 300	(t _{sample} /24)	(t _{sample} /24) + 300	(t _{sample} /24) - 300	(t _{sample} /24)	(t _{SAMPLE} /24) + 300	(t _{sample} /24) - 300	(t _{SAMPLE} /24)	(t _{SAMPLE} /24) + 300	ps
DCO to FCO Delay $(t_{\text{FRAME}})^4$	Full	(t _{sample} /24) - 300	(t _{SAMPLE} /24)	(t _{sample} /24) + 300	(t _{sample} /24) - 300	(t _{SAMPLE} /24)	(t _{SAMPLE} /24) + 300	(t _{SAMPLE} /24) - 300	(t _{SAMPLE} /24)	(t _{SAMPLE} /24) + 300	ps
Data to Data Skew (t _{DATA-MAX} – t _{DATA-MIN})	Full		±50	±200		±50	±200		±50	±200	ps
Wake-Up Time (Standby)	25°C		600			600			600		ns
Wake-Up Time (Power-Down)	25°C		375			375			375		μs
Pipeline Latency	Full		8			8			8		CLK
											cycles
APERTURE											
Aperture Delay (t _A)	25°C		750			750			750		ps
Aperture Uncertainty (Jitter)	25°C		<1			<1			<1		ps
	25%		1			1			1		rms
Out-of-kange Recovery Time	25°C		I			I			I		cycles

¹ See the AN-835 Application Note, Understanding High Speed ADC Testing and Evaluation, for a complete set of definitions and how these tests were completed.

² This can be adjusted via the SPI interface.

³ Measurements were made using a part soldered to FR4 material. ⁴ t_{SAMPLE}/24 is based on the number of bits divided by 2 because the delays are based on half duty cycles.



Figure 3. 10-Bit Data Serial Stream, MSB First

Data Sheet



Figure 4. 12-Bit Data Serial Stream, LSB First

ABSOLUTE MAXIMUM RATINGS

Table 5.

	With	
Parameter	Respect To	Rating
ELECTRICAL		
AVDD	AGND	–0.3 V to +2.0 V
DRVDD	DRGND	–0.3 V to +2.0 V
AGND	DRGND	–0.3 V to +0.3 V
AVDD	DRVDD	-2.0 V to +2.0 V
Digital Outputs	DRGND	–0.3 V to +2.0 V
(D + x, D - x, DCO+,		
DCO–, FCO+, FCO–)		
CLK+, CLK–	AGND	–0.3 V to +3.9 V
VIN + x, VIN - x	AGND	–0.3 V to +2.0 V
SDIO/ODM	AGND	–0.3 V to +2.0 V
PDWN, SCLK/DTP, CSB	AGND	–0.3 V to +3.9 V
REFT, REFB, RBIAS	AGND	–0.3 V to +2.0 V
VREF, SENSE	AGND	–0.3 V to +2.0 V
ENVIRONMENTAL		
Operating Temperature Range (Ambient)		–40°C to +85°C
Maximum Junction Temperature		150°C
Lead Temperature (Soldering, 10 sec)		300°C
Storage Temperature Range (Ambient)		–65°C to +150°C

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

THERMAL IMPEDANCE

Table 6.

Air Flow Velocity (m/s)	θ_{JA}^{1}	θյβ	θις
0.0	17.7°C/W		
1.0	15.5°C/W	8.7°C/W	0.6°C/W
2.5	13.9°C/W		

 $^1\,\theta_{JA}$ for a 4-layer PCB with solid ground plane (simulated). Exposed pad soldered to PCB.

ESD CAUTION



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS



Figure 5. 64-Lead LFCSP Pin Configuration, Top View

Table 7. Pin Function Descriptions

Pin No.	Mnemonic	Description
0	AGND	Analog Ground (Exposed Paddle)
1, 4, 7, 8, 11, 12, 37, 42, 45, 48, 51, 59, 62	AVDD	1.8 V Analog Supply
13, 36	DRGND	Digital Output Driver Ground
14, 35	DRVDD	1.8 V Digital Output Driver Supply
2	VIN + G	ADC G Analog Input True
3	VIN – G	ADC G Analog Input Complement
5	VIN – H	ADC H Analog Input Complement
6	VIN + H	ADC H Analog Input True
9	CLK–	Input Clock Complement
10	CLK+	Input Clock True
15	D – H	ADC H Digital Output Complement
16	D+H	ADC H Digital Output True
17	D – G	ADC G Digital Output Complement
18	D + G	ADC G Digital Output True
19	D – F	ADC F Digital Output Complement
20	D + F	ADC F Digital Output True
21	D – E	ADC E Digital Output Complement
22	D + E	ADC E Digital Output True
23	DCO-	Data Clock Digital Output Complement
24	DCO+	Data Clock Digital Output True
25	FCO-	Frame Clock Digital Output Complement
26	FCO+	Frame Clock Digital Output True
27	D – D	ADC D Digital Output Complement
28	D + D	ADC D Digital Output True
29	D – C	ADC C Digital Output Complement
30	D + C	ADC C Digital Output True
31	D – B	ADC B Digital Output Complement
32	D + B	ADC B Digital Output True

Pin No.	Mnemonic	Description
33	D – A	ADC A Digital Output Complement
34	D + A	ADC A Digital Output True
38	SCLK/DTP	Serial Clock/Digital Test Pattern
39	SDIO/ODM	Serial Data Input-Output/Output Driver Mode
40	CSB	Chip Select Bar
41	PDWN	Power Down
43	VIN + A	ADC A Analog Input True
44	VIN – A	ADC A Analog Input Complement
46	VIN – B	ADC B Analog Input Complement
47	VIN + B	ADC B Analog Input True
49	VIN + C	ADC C Analog Input True
50	VIN – C	ADC C Analog Input Complement
52	VIN – D	ADC D Analog Input Complement
53	VIN + D	ADC D Analog Input True
54	RBIAS	External Resistor to Set the Internal ADC Core Bias Current
55	SENSE	Reference Mode Selection
56	VREF	Voltage Reference Input/Output
57	REFB	Differential Reference (Negative)
58	REFT	Differential Reference (Positive)
60	VIN + E	ADC E Analog Input True
61	VIN – E	ADC E Analog Input Complement
63	VIN – F	ADC F Analog Input Complement
64	VIN + F	ADC F Analog Input True

EQUIVALENT CIRCUITS



























Figure 13. Equivalent SENSE Circuit

TYPICAL PERFORMANCE CHARACTERISTICS



Figure 15. Single-Tone 32k FFT with $f_{IN} = 2.3$ MHz, AD9222-40



Figure 16. Single-Tone 32k FFT with $f_{IN} = 19.7$ MHz, AD9222-40



Figure 17. Single-Tone 32k FFT with $f_{IN} = 2.3$ MHz, AD9222-50



Figure 18. Single-Tone 32k FFT with $f_{IN} = 35$ MHz, AD9222-50



Figure 19. Single-Tone 32k FFT with $f_{IN} = 70$ MHz, AD9222-50



Figure 20. Single-Tone 32k FFT with $f_{IN} = 120$ MHz, AD9222-50

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Figure 21. Single-Tone 32k FFT with $f_{IN} = 2.3$ MHz, AD9222-65



Figure 22. Single-Tone 32k FFT with $f_{IN} = 35$ MHz, AD9222-65



Figure 23. Single-Tone 32k FFT with $f_{IN} = 70$ MHz, AD9222-65



Figure 24. Single-Tone 32k FFT with $f_{IN} = 120$ MHz, AD9222-65



Figure 25. SNR/SFDR vs. f_{SAMPLE} , $f_{IN} = 2.61$ MHz, AD9222-50



AD9222



Figure 27. SNR/SFDR vs. f_{SAMPLE}, f_{IN} = 2.3 MHz, AD9222-65





Figure 29. SNR/SFDR vs. Analog Input Level, $f_{IN} = 10.3$ MHz, AD9222-50



Figure 30. SNR/SFDR vs. Analog Input Level, $f_{IN} = 10.3$ MHz, AD9222-65



Figure 31. SNR/SFDR vs. Analog Input Level, $f_{IN} = 35$ MHz, AD9222-50



Figure 32. SNR/SFDR vs. Analog Input Level, f_{IN} = 35 MHz, AD9222-65

Data Sheet

0 AIN1 AND AIN2 = -7dBFS SFDR = 89.87dB IMD2 = 96.07dBc IMD3 = 90.16dBc -20 -40 AMPLITUDE (dBFS) -60 -80 -100 -120 05967-025 0 2 4 6 8 10 12 14 16 18 20 FREQUENCY (MHz)

Figure 33. Two-Tone 32k FFT with $f_{IN1} = 15$ MHz and $f_{IN2} = 16$ MHz, AD9222-40



Figure 34. Two-Tone 32k FFT with $f_{\rm IN1}$ = 70 MHz and $f_{\rm IN2}$ = 71 MHz, AD9222-40



Figure 35. Two-Tone 32k FFT with $f_{IN1} = 15$ MHz and $f_{IN2} = 16$ MHz, AD9222-50



Figure 36. Two-Tone 32k FFT with $f_{IN1} = 70$ MHz and $f_{IN2} = 71$ MHz, AD9222-50



Figure 37. Two-Tone 32k FFT with $f_{IN1} = 15$ MHz and $f_{IN2} = 16$ MHz, AD9222-65



Figure 38. Two-Tone 32k FFT with $f_{IN1} = 70$ MHz and $f_{IN2} = 71$ MHz, AD9222-65

05967-096

05967-031

6

05967

80



Figure 41. SINAD/SFDR vs. Temperature, $f_{IN} = 2.61$ MHz, AD9222-50



Data Sheet









Figure 52. Noise Power Ratio (NPR), AD9222-50

THEORY OF OPERATION

The AD9222 architecture consists of a pipelined ADC divided into three sections: a 4-bit first stage followed by eight 1.5-bit stages and a final 3-bit flash. Each stage provides sufficient overlap to correct for flash errors in the preceding stage. The quantized outputs from each stage are combined into a final 12-bit result in the digital correction logic. The pipelined architecture permits the first stage to operate with a new input sample while the remaining stages operate with preceding samples. Sampling occurs on the rising edge of the clock.

Each stage of the pipeline, excluding the last, consists of a low resolution flash ADC connected to a switched-capacitor DAC and an interstage residue amplifier (for example, a multiplying digital-to-analog converter (MDAC)). The residue amplifier magnifies the difference between the reconstructed DAC output and the flash input for the next stage in the pipeline. One bit of redundancy is used in each stage to facilitate digital correction of flash errors. The last stage simply consists of a flash ADC.

The output staging block aligns the data, corrects errors, and passes the data to the output buffers. The data is then serialized and aligned to the frame and data clocks.

ANALOG INPUT CONSIDERATIONS

The analog input to the AD9222 is a differential switched-capacitor circuit designed for processing differential input signals. This circuit can support a wide common-mode range while maintaining excellent performance. An input common-mode voltage of midsupply minimizes signal-dependent errors and provides optimum performance.



Figure 54. Switched-Capacitor Input Circuit

The clock signal alternately switches the input circuit between sample mode and hold mode (see Figure 54). When the input circuit is switched into sample mode, the signal source must be capable of charging the sample capacitors and settling within one-half of a clock cycle. A small resistor in series with each input can help reduce the peak transient current injected from the output stage of the driving source. In addition, low-Q inductors or ferrite beads can be placed on each leg of the input to reduce high differential capacitance at the analog inputs and therefore achieve the maximum bandwidth of the ADC. Such use of low-Q inductors or ferrite beads is required when driving the converter front end at high IF frequencies. Either a shunt capacitor or two single-ended capacitors can be placed on the inputs to provide a matching passive network. This ultimately creates a low-pass filter at the input to limit unwanted broadband noise. See the AN-742 Application Note, the AN-827 Application Note, and the Analog Dialogue article "Transformer-Coupled Front-End for Wideband A/D Converters" (Volume 39, April 2005) for more information. In general, the precise values depend on the application.

The analog inputs of the AD9222 are not internally dc-biased. Therefore, in ac-coupled applications, the user must provide this bias externally. Setting the device so that $V_{CM} = AVDD/2$ is recommended for optimum performance, but the device can function over a wider range with reasonable performance, as shown in Figure 55 and Figure 57.



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For best dynamic performance, the source impedances driving VIN + x and VIN – x should be matched such that commonmode settling errors are symmetrical. These errors are reduced by the common-mode rejection of the ADC. An internal reference buffer creates the positive and negative reference voltages, REFT and REFB, respectively, that define the span of the ADC core. The output common-mode of the reference buffer is set to midsupply, and the REFT and REFB voltages and span are defined as

REFT = 1/2 (AVDD + VREF)REFB = 1/2 (AVDD - VREF) $Span = 2 \times (REFT - REFB) = 2 \times VREF$

It can be seen from these equations that the REFT and REFB voltages are symmetrical about the midsupply voltage and, by definition, the input span is twice the value of the VREF voltage.

Maximum SNR performance is achieved by setting the ADC to the largest span in a differential configuration. In the case of the AD9222, the largest input span available is 2 V p-p.

Differential Input Configurations

There are several ways to drive the AD9222 either actively or passively; however, optimum performance is achieved by driving the analog input differentially. For example, using the AD8334 differential driver to drive the AD9222 provides excellent performance and a flexible interface to the ADC (see Figure 62) for baseband applications. This configuration is commonly used for medical ultrasound systems.

For applications where SNR is a key parameter, differential transformer coupling is the recommended input configuration (see Figure 59 and Figure 60) because the noise performance of most amplifiers is not adequate to achieve the true performance of the AD9222.

Regardless of the configuration, the value of the shunt capacitor, C, is dependent on the input frequency and may need to be reduced or removed.



Figure 60. Differential Transformer-Coupled Configuration for IF Applications

Single-Ended Input Configuration

A single-ended input may provide adequate performance in cost-sensitive applications. In this configuration, SFDR and distortion performance degrade due to the large input common-mode swing. If the application requires a single-ended input configuration, ensure that the source impedances on each input are well matched in order to achieve the best possible performance. A full-scale input of 2 V p-p can still be applied to the ADC's VIN + x pin while the VIN – x pin is terminated. Figure 61 details a typical single-ended input configuration.



Figure 61. Single-Ended Input Configuration



Figure 62. Differential Input Configuration Using the AD8334

CLOCK INPUT CONSIDERATIONS

For optimum performance, the AD9222 sample clock inputs (CLK+ and CLK-) should be clocked with a differential signal. This signal is typically ac-coupled to the CLK+ and CLK- pins via a transformer or capacitors. These pins are biased internally and require no additional biasing.

Figure 63 shows a preferred method for clocking the AD9222. The low jitter clock source is converted from a single-ended signal to a differential signal using an RF transformer. The back-toback Schottky diodes across the secondary transformer limit clock excursions into the AD9222 to approximately 0.8 V p-p differential. This helps prevent the large voltage swings of the clock from feeding through to other portions of the AD9222, and it preserves the fast rise and fall times of the signal, which are critical to low jitter performance.



Figure 63. Transformer-Coupled Differential Clock

Another option is to ac-couple a differential PECL signal to the sample clock input pins as shown in Figure 64. The AD9510/AD9511/AD9512/AD9513/AD9514/AD9515 family of clock drivers offers excellent jitter performance.





that retimes the nonsampling edge, providing an internal clock signal with a nominal 50% duty cycle. This allows a wide range of clock input duty cycles without affecting the performance of the AD9222. When the DCS is on, noise and distortion performance are nearly flat for a wide range of duty cycles. However, some applications may require the DCS function to be off. If so, keep in mind that the dynamic range performance can be affected when operated in this mode. See the Memory Map section for more details on using this feature.

The duty cycle stabilizer uses a delay-locked loop (DLL) to create the nonsampling edge. As a result, any changes to the sampling frequency require approximately eight clock cycles to allow the DLL to acquire and lock to the new rate.

In some applications, it is acceptable to drive the sample clock inputs with a single-ended CMOS signal. In such applications, CLK+ should be directly driven from a CMOS gate, and the CLK– pin should be bypassed to ground with a 0.1 μ F capacitor in parallel with a 39 k Ω resistor (see Figure 66). Although the CLK+ input circuit supply is AVDD (1.8 V), this input is designed to withstand input voltages of up to 3.3 V, making the selection of the drive logic voltage very flexible.



Figure 67. Single-Ended 3.3 V CMOS Sample Clock

0.1µF

CLK-

Clock Duty Cycle Considerations

¹50Ω RESISTOR IS OPTIONAL